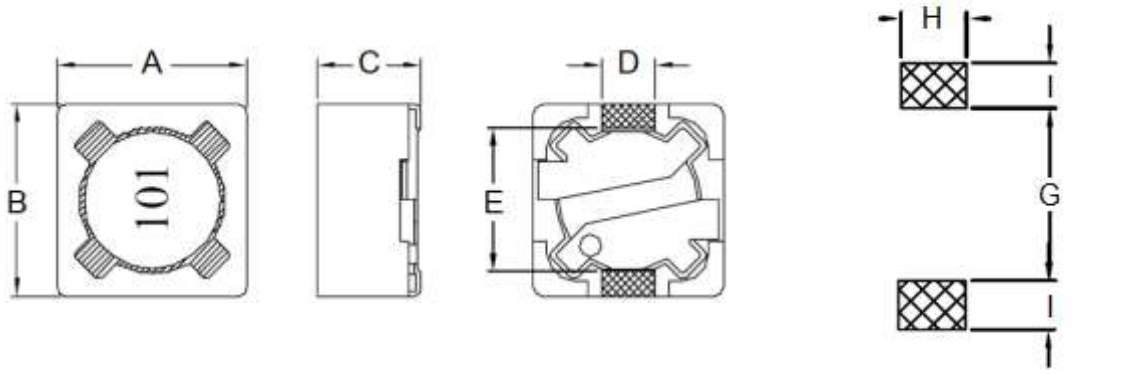
1. Part No. Expression

S D C 0 7 0 4 1 0 0 M F

(a) (b) (c) (d) (e)

(a) Series Code
(b) Dimension Code
(c) Inductance Code
(d) Tolerance Code
(e) Packaging Code

2. Configuration & Dimensions (Unit: mm)

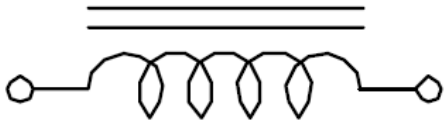


Recommended PCB Layout

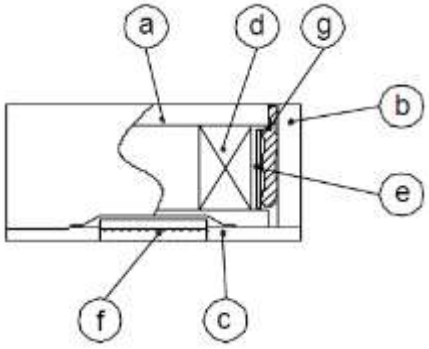
Note: 1. The above PCB layout reference only.
2. Marking: Inductance Code

A	B	C	D	E	G	H	I
7.3±0.2	7.3±0.2	4.5 Max	1.8 Ref	5.0 Ref	4.8 Ref	2.2 Ref	1.6 Ref

3. Schematic



4. Material List



(a) Core
(b) Core
(c) Base
(d) Wire
(e) Tape
(f) Terminal
(g) Adhesive

5. General Specifications

(a) Operating Temp.: -30°C to +105°C (including self-temperature rise)
(b) All test data referenced to 25°C ambient.
(c) Heat Rated Current (Irms) will cause the coil temperature rise ΔT of 40°C Max.
(d) Saturation Current (Isat) will cause inductance L0 to drop 25% Max.
(e) Rated Current: The lower value of Isat and Irms.
(f) Resistance to solder heat: 260° C, 10 secs
(g) Storage Condition (Component in its packaging)
    i) Temperature: -10°C to 40°C
    ii) Humidity: Less than 60% RH

NOTE: Specifications subject to change without notice. Please check our website for latest information.

6. Electrical Characteristics

Part Number	Inductance (uH) @0A ±20%	Test Frequency	DCR (Ω) Max	IDC (A) Max
SDC0704100MF	10	0.25V/1KHz	0.049	1.84
SDC0704120MF	12	0.25V/1KHz	0.058	1.71
SDC0704150MF	15	0.25V/1KHz	0.081	1.47
SDC0704180MF	18	0.25V/1KHz	0.091	1.31
SDC0704220MF	22	0.25V/1KHz	0.110	1.23
SDC0704270MF	27	0.25V/1KHz	0.150	1.12
SDC0704330MF	33	0.25V/1KHz	0.170	0.96
SDC0704390MF	39	0.25V/1KHz	0.230	0.91
SDC0704470MF	47	0.25V/1KHz	0.260	0.88
SDC0704560MF	56	0.25V/1KHz	0.350	0.75
SDC0704680MF	68	0.25V/1KHz	0.380	0.69
SDC0704820MF	82	0.25V/1KHz	0.430	0.61
SDC0704101MF	100	0.25V/1KHz	0.610	0.60
SDC0704121MF	120	0.25V/1KHz	0.660	0.52
SDC0704151MF	150	0.25V/1KHz	0.880	0.46
SDC0704181MF	180	0.25V/1KHz	0.980	0.42
SDC0704221MF	220	0.25V/1KHz	1.170	0.36
SDC0704271MF	270	0.25V/1KHz	1.640	0.34
SDC0704331MF	330	0.25V/1KHz	1.860	0.32
SDC0704391MF	390	0.25V/1KHz	2.850	0.29
SDC0704471MF	470	0.25V/1KHz	3.010	0.26
SDC0704561MF	560	0.25V/1KHz	3.620	0.23
SDC0704681MF	680	0.25V/1KHz	4.630	0.22
SDC0704821MF	820	0.25V/1KHz	5.200	0.20
SDC0704102MF	1000	0.25V/1KHz	6.000	0.18

NOTE: Specifications subject to change without notice. Please check our website for latest information.

7. Soldering Specification

Mildly activated rosin fluxes are preferred. Our terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

7-1. IR Soldering Reflow

Recommended temperature profiles for lead free re-flow soldering in Figure 1, Table 1.1 & 1.2 (J-STD-020F).

7-2. Iron Reflow

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended (Figure 2).

Note:

(a) Preheat circuit and products to 150°C.

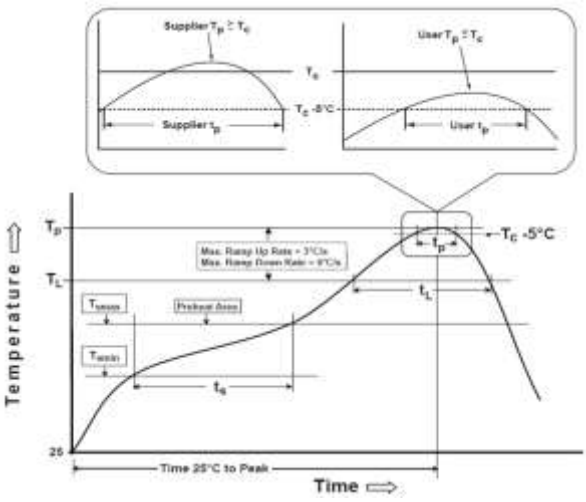
(b) 350°C tip temperature (Max.)

(c) Never contact the ceramic with the iron tip

(d) 1.0mm tip diameter (Max.)

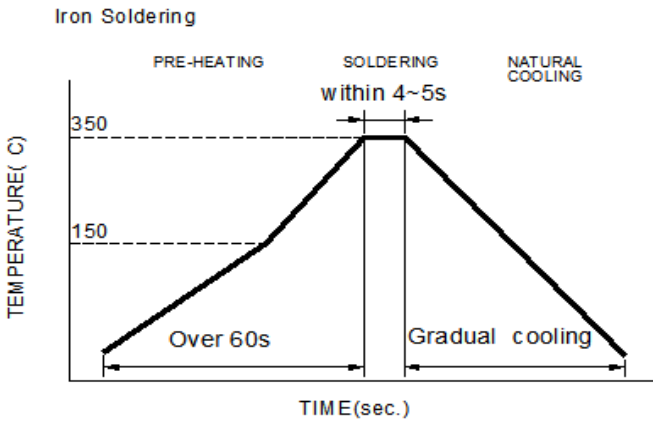
(e) Use a 20 watt soldering iron with tip diameter of 1.0mm

(f) Limit soldering time to 4~5 sec.



Reflow times: 3 times Max

Figure 1: IR Soldering Reflow



Iron Soldering times：1 times max

Figure 2: Iron soldering temperature profiles

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Table (1.1) Reflow Profiles

Profile Type:	Pb-Free Assembly
Preheat -Temperature Min (T_{smin}) -Temperature Max (T_{smax}) -Time (t_s) from (T_{smin} to T_{smax})	 150°C 200°C 60-120seconds
Ramp-up rate ($T_L$to T_p)	3°C /second max.
Liquids temperature (T_L) Time (t_L) maintained above T_L	217°C 60-150 seconds
Classification temperature (T_c)	See Table (1.2)
Time (t_p) at Tc- 5°C (Tp should be equal to or less than Tc.)	< 30 seconds
Ramp-down rate (T_p to T_L)	6°C /second max.
Time 25°C to peak temperature	8 minutes max.

Tp: maximum peak package body temperature, **Tc**: the classification temperature.

For user (customer) **Tp** should be equal to or less than **Tc.**

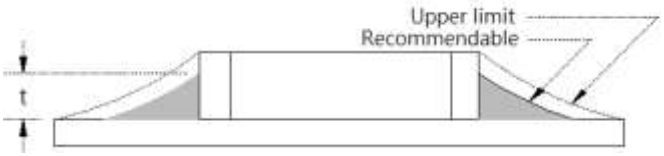
Table (1.2) Package Thickness/Volume and Classification Temperature (T_c)

	Package Thickness	Volume mm^3 <350	Volume mm^3 350-2000	Volume mm^3 >2000
PB-Free Assembly	<1.6mm	260°C	260°C	260°C
	1.6-2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

Reflow is referred to standard IPC/JEDEC J-STD-020F.

7-3. Soldering Volume

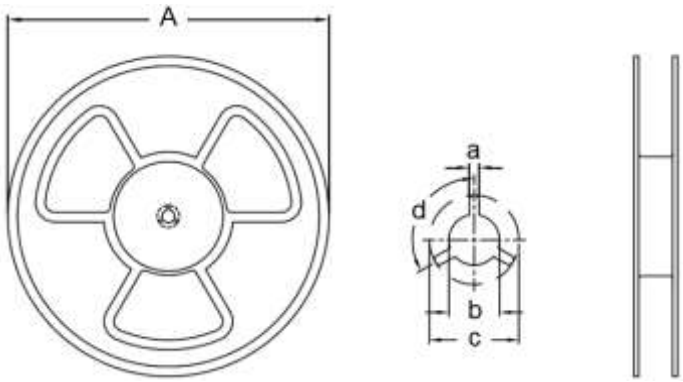
Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance. Solder shall be used not to be exceeded as shown in the Figure below. Minimum fillet height = soldering thickness + 25% product height.



NOTE: Specifications subject to change without notice. Please check our website for latest information.

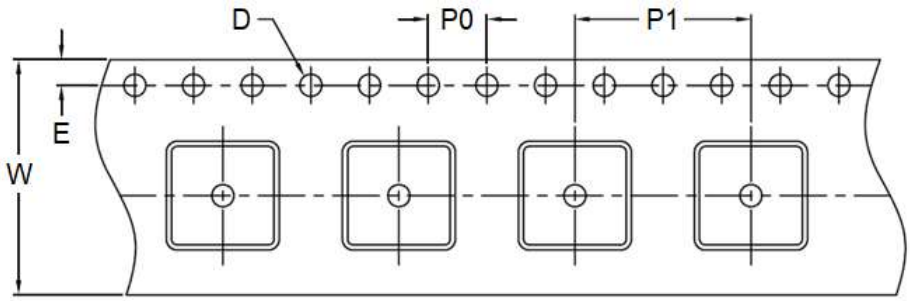
8. Packaging Information

8-1. Reel Dimension (Unit: mm)

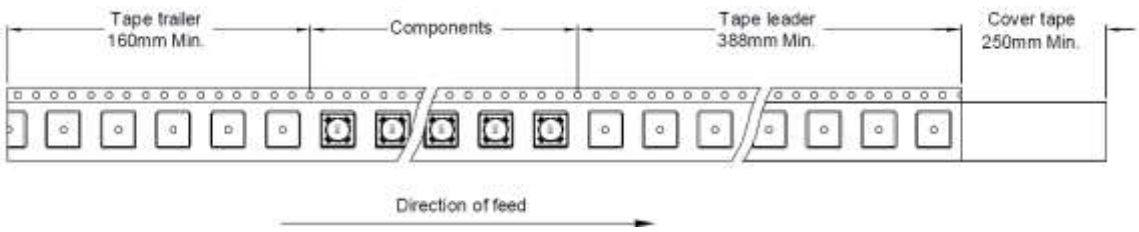


Type	A	a	b	c	d
13”x16mm	330.0 Ref	2.5 Ref	13.0 Ref	23.0 Ref	120°

8-2. Tape Dimension (Unit: mm)



W	E	D	P0	P1
16.00 Ref	1.75±0.10	1.50+0.10/-0.00	4.00±0.10	12.00 Ref

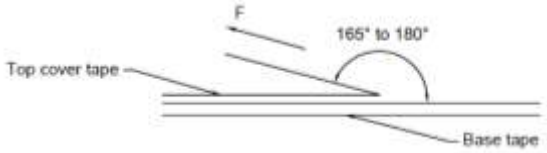


NOTE: Specifications subject to change without notice. Please check our website for latest information.

8-3. Packaging Quantity (Unit: Pcs)

INNER : REEL		OUTER : CARTON		
QTY(PCS)	G.W(gw)	QTY(PCS)	G.W(Kg)	SIZE(cm)
1,000	1.2	16,000	24	36x36x40

8-4. Tearing Off Force



The force for tearing off cover tape is according to the follow table, in the arrow direction under the following conditions.
(Referenced ANSI/EIA-481-D-2008 of 4.11 standard)

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed (mm/min)
5~35	45~85	860~1060	300±10

Tape Size	8 mm	12 to 56 mm	72 mm or Wider
Tearing Off Force (grams)	10~100	10~130	10~150

Application Notice

1. Storage Conditions

To maintain the solderability of terminal electrodes:

(a) Products meet IPC/JEDEC J-STD-020F standard-MSL, level 1.

(b) Recommended products should be used within 12 months from the time of delivery.

(c) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation

(a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.

(b) Vacuum pick up is strongly recommended for individual components.

(c) Bulk handling should ensure that abrasion and mechanical shock are minimized.